

[INCREASE PRODUCTIVITY AT WAFER TEST USING PROBE RETEST DATA ANALYSIS]

Abstract

Disclosed is a method and system for wafer/probe testing of integrated circuit devices after manufacture. The invention begins by testing an initial group of devices (e.g., integrated circuit chips) to produce an initial failing group of devices that failed the testing. The devices in the initial failing group are identified by type of failure. Then, the invention retests the devices in the initial failing group to identify a retested passing group of devices that passed the retesting. Next, the invention analyzes the devices in the retested passing group which allows the invention to produce statistics regarding the likelihood that a failing device that failed the initial testing will pass the retesting according to the type of failure. Then, the invention evaluates these statistics to determine which types of failures have retest passing rates above a predetermined threshold. From this, the invention produces a database comprising an optimized retest table listing the types of defects that are approved for retesting.